

For immediate release

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The New Stratus 200 and Stratus 300 Provides Highest Throughput Electrodeposition System with Maximum Wafer Yield

Billerica, MA – July 10, 2006– NEXX Systems, a leading provider of processing equipment for advanced wafer level packaging applications, is pleased to introduce the Stratus 200 and Stratus 300 fully automated electrodeposition systems. The Stratus 200 is capable of processing 100mm to 200mm wafers, and the Stratus 300 is capable of processing 200mm and 300mm wafers. The Stratus is a highly flexible and configurable tool that offers outstanding process capability in a simple, reliable system architecture. Designed to satisfy the particular challenges of thick metal deposition applications (such as tin lead solder, copper pillars, copper redistribution layers, lead-free solder, and gold bump), the Stratus 200 and Stratus 300 offer the highest throughput with maximum yield. The unique ShearPlate™ deposition module maximizes yield for high aspect ratio bumps while minimizing cost of materials.

Stratus 200 electrodeposition systems have been installed at wafer level packaging production facilities in the US, Malaysia and Taiwan.

Stated Arthur Keigler, Vice President of Technology, NEXX Systems, "The Stratus was specifically designed to meet the process challenges and cost constraints of the advanced packaging industry. Unlike other electrodeposition tools, the Stratus was conceived as an economical, flexible, high throughput system providing process superiority for packaging applications."

A clear benefit of the Stratus 200 and Stratus 300 is the lowest cost of ownership in the industry. Housed in configurable and scalable architecture, the Stratus offers superior economies for NEXX customers. High throughput, optimum deposition conditions, and no wafer breakage translate to maximum yield, resulting in the most cost-effective electrodeposition processing available. A simple, low-cost anode design, easy access for maintenance, and modular fluid-handling components, all further enhance the outstanding operational cost advantages of Stratus electrodeposition.

Modular architecture: The Stratus' modular architecture permits a wide variety of processes. Wafers are processed two at a time, loaded in a back-to-back wafer holder at the load station. The load station checks the wafer seal integrity after each wafer is in place; this

seal check eliminates the possibility of misloads that create costly scrap wafers. Once the wafer holder is loaded, it is moved to the process modules. Each process module – only 8 inches wide – contains an independently-controlled process chemistry. A complementary number of rinse modules – less than 8 inches wide – are integrated in the process flow to ensure maximum throughput.

Up to 21 process modules (42 wafer process positions) can be configured in any combination, thus permitting virtually limitless process variations to meet changing demands. This flexible, modular line configuration also permits multi-layer metal or alloy plating with no loading or unloading of the wafers between processes. Deposition or other process modules can be configured anywhere in the process chain.

Incorporating the proven Stratus process cell design, Stratus 200/300 offers multiple wafer size capability plus the added feature of rapid size change with minimal downtime. An advanced pre-wet module wets deep-featured wafers prior to plating to ensure superior metallization.

Patented Wafer Holder and Contact Ring Seal: The Stratus successfully overcomes two critical, yet inherent technical limitations of traditional electroplating technology. The Stratus' modular, vertical architecture is built around a wafer holder that simultaneously creates both a fluid seal and a virtually continuous electrical contact to the wafer surface perimeter. Two wafers are held back-to-back in a fail-safe configuration. The wafer holder achieves precise alignment between the wafer and critical process elements, enabling small process cell size and more space-efficient system configurations. The Stratus' patented contact ring seal provides a leak tight, uniform, self-checking seal of the wafer in the wafer holder. The uniform electrical contact ensures uniform deposition on the wafer surface, while simultaneously eliminating any fluid leakage (and resulting metal deposition) on the backside of the wafer.

Thinnest Diffusion Boundary Layer: The second critical parameter is the fluid boundary layer at the wafer surface. This boundary layer impedes the diffusion of ions in the chemical bath, thus slowing deposition times in what are already long deposition processes. The Stratus' patent-pending ShearPlate technology creates programmable fluid agitation less than 2 mm from the surface of the wafer, resulting the thinnest, most uniform diffusion boundary layer in the industry – as much as four times thinner than competing technologies. Unlike fountain cell platers, there is no radial non-uniformity to the boundary layer; hence, there is no need to compensate with expensive multi-zone anodes. The ShearPlate, moving rapidly up and down near the wafer's surface, creates the vigorous fluid motion on the surface necessary to enable metal ions and additives to successfully penetrate high aspect ratio bumps and deep photoresist patterns. The ShearPlate ensures the composition of

alloys, such as SnPb and SnAg, is maintained across the wafer and, combined with vertical wafer orientation, avoids trapped gas bubbles inherent in horizontal plating technologies. The result is void-free bumps across the wafer surface. The results of these two achievements are process superiority – better yield in difficult applications – and high throughput.

About NEXX: NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electrodeposition of metals. Additional information can be found at: www.nexxsystems.com.

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